

MATERIAL DECLARATION SHEET

BOURNS®

Material	MF-NSML Series
Product Line	Multifuse
Revision Date	May. 3, 2013
Revision	C
RoHS Compliant	Yes
Halogen Free Compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Metal Carbide	Titanium Carbide	0.0065833	12070-08-5	43.281%	43.281%
2	Copper Plating	Copper	0.0010606	7440-50-8	6.973%	6.973%
3	Foil	Copper	0.0029675	7440-50-8	19.509%	20.536%
		Nickel	0.0001562	7440-02-0	1.027%	
4	PCB Foil	Copper	0.0017619	7440-50-8	11.583%	11.583%
5	Polymer	Polyethylene Homopolymer	0.0005165	9002-88-4	3.396%	3.401%
		Proprietary Additives	0.0000008	-	0.005%	
6	Prepreg	Epoxy	0.0011975	35948-25-5	7.873%	12.045%
		Glass fiber	0.0006346	65997-17-3	4.172%	
7	Soldering Plating	Tin	0.0003258	7440-31-5	2.142%	2.142%
8	Marking	Epoxy	0.0000039	25068-38-6	0.026%	0.039%
		Titanium Dioxide	0.0000020	1317-80-2	0.013%	
		Total Weight (%)				

Total weight (grams)	0.0152084	Total	100%	100%
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